

## WST2305-VB Datasheet P-Channel 20-V (D-S) MOSFET

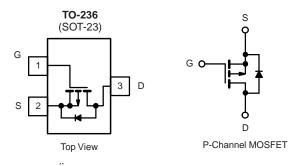
| PRODUCT SUMMARY                                   |        |  |  |  |  |
|---|--------|--|--|--|--|
| V <sub>DS</sub> (V)                               | - 20   |  |  |  |  |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$ | 0.034  |  |  |  |  |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = -2.5 \text{ V}$ | 0.046  |  |  |  |  |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = -1.8 \text{ V}$ | 0.067  |  |  |  |  |
| I <sub>D</sub> (A)                                | - 5    |  |  |  |  |
| Configuration                                     | Single |  |  |  |  |

#### **FEATURES**

- **Halogen-free Option Available**
- Trench Power MOSFET

# COMPLIANT HALOGEN FREE

APPLICATIONSLoad Switch for Portable Devices



| ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted) |                         |  |               |    |  |
|---|-------------------------|--|---------------|----|--|
| PARAMETER   | SYMBOL                  | LIMIT                                    | UNIT          |    |  |
| Drain-Source Voltage  |                         | $V_{DS}$                                 | - 20          | V  |  |
| Gate-Source Voltage   |                         | V <sub>GS</sub>                          | ± 8           | V  |  |
| Continuous Drain Current  | T <sub>C</sub> = 25 °C  | 1  | - 5           |    |  |
|   | T <sub>C</sub> = 125 °C | - I <sub>D</sub>                         | - 3           |    |  |
| Continuous Source Current (Diode Conduct                                  | I <sub>S</sub>          | - 2.5                                    | Α             |    |  |
| Pulsed Drain Current <sup>a</sup>   |                         | I <sub>DM</sub>                          | - 20          |    |  |
| Single Pulse Avalanche Current  | . 0.4                   | I <sub>AS</sub>                          | - 11          |    |  |
| Single Pulse Avalanche Energy   | L = 0.1 mH              | E <sub>AS</sub>                          | 6             | mJ |  |
| Maximum Power Dissipation <sup>a</sup>                                    | T <sub>C</sub> = 25 °C  | $T_{C} = 25 °C$ $T_{C} = 125 °C$ $P_{D}$ | 2             | W  |  |
|   | T <sub>C</sub> = 125 °C |  | 0.67          | VV |  |
| Operating Junction and Storage Temperature Range                          |                         | T <sub>J</sub> , T <sub>stq</sub>        | - 55 to + 175 | °C |  |

| THERMAL RESISTANCE RATINGS |                        |            |       |       |
|----------------------------|------------------------|------------|-------|-------|
| PARAMETER                  |                        | SYMBOL     | LIMIT | UNIT  |
| Junction-to-Ambient        | PCB Mount <sup>b</sup> | $R_{thJA}$ | 175   | °C/W  |
| Junction-to-Foot (Drain)   |                        | $R_{thJF}$ | 75    | C/ VV |



| PARAMETER                                     | SYMBOL                   | TEST CONDITIONS   |  | MIN. | TYP.  | MAX.  | UNIT |
|---|--------------------------|---|--|------|-------|-------|------|
| Static  |                          |   |  |      |       | ı     |      |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>          | $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$  |  | - 20 | -     | -     | V    |
| Gate-Source Threshold Voltage                 | V <sub>GS(th)</sub>      | V <sub>DS</sub> =   | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$                                    |      | -     | - 1   | v    |
| Gate-Source Leakage                           | I <sub>GSS</sub>         | V <sub>DS</sub> =   | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$                         |      | -     | ± 100 | nA   |
|   |                          | $V_{GS} = 0 V$  | V <sub>DS</sub> = - 12 V   | -    | -     | - 1   |      |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>         | $V_{GS} = 0 V$  | V <sub>DS</sub> = - 12 V, T <sub>J</sub> = 125 °C                        | 1    | -     | - 50  | μΑ   |
|   |                          | $V_{GS} = 0 V$  | V <sub>DS</sub> = - 12 V, T <sub>J</sub> = 175 °C                        | -    | -     | - 150 |      |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>       | V <sub>GS</sub> = - 4.5 V   | $V_{DS} \le -5 V$  | - 10 | -     | -     | Α    |
|   |                          | V <sub>GS</sub> = - 4.5 V   | I <sub>D</sub> = - 3.5 A   | -    | 0.034 | -     | Ω    |
|   |                          | $V_{GS} = -4.5 \text{ V}$   | I <sub>D</sub> = - 3.5 A, T <sub>J</sub> = 125 °C                        | -    | 0.066 | -     |      |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>      | $V_{GS} = -4.5 \text{ V}$   | I <sub>D</sub> = - 3.5 A, T <sub>J</sub> = 175 °C                        | 1    | 0.075 | -     |      |
|   |                          | $V_{GS} = -2.5 \text{ V}$   | I <sub>D</sub> = - 3 A   | 1    | 0.046 | -     |      |
|   |                          | V <sub>GS</sub> = - 1.8 V   | I <sub>D</sub> = - 2 A   | 1    | 0.067 | -     |      |
| Forward Transconductance <sup>b</sup>         | 9 <sub>fs</sub>          | V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 1.6 A   |  | ı    | 7     | -     | S    |
| Dynamic <sup>b</sup>                          |                          |   |  |      |       |       |      |
| Input Capacitance                             | C <sub>iss</sub>         |   |  | 1    | 695   | 870   |      |
| Output Capacitance                            | C <sub>oss</sub>         | $V_{GS} = 0 V$  | $V_{DS} = -6 \text{ V}, f = 1 \text{ MHz}$                               |      | 265   | 335   | pF   |
| Reverse Transfer Capacitance                  | $C_{rss}$                |   |  | =    | 190   | 240   |      |
| Total Gate Charge <sup>c</sup>                | Qg                       |   |  | 1    | 8.4   | 13    |      |
| Gate-Source Charge <sup>c</sup>               | $Q_{gs}$                 | $V_{GS} = -4.5 \text{ V}$   | $V_{GS} = -4.5 \text{ V}$ $V_{DS} = -6 \text{ V}, I_D = -3.85 \text{ A}$ |      | 1     | -     | nC   |
| Gate-Drain Charge <sup>c</sup>                | $Q_{gd}$                 |   |  |      | 2.4   | -     |      |
| Gate Resistance                               | $R_{g}$                  | f = 1 MHz   |  | 4.1  | 8.2   | 12.3  | Ω    |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>       |   |  | 1    | 17    | 26    |      |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>           | $V_{DD} = -6 \text{ V}, R_L = 1.6 \Omega$ $I_D \cong -3.85 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$ |  | -    | 19    | 29    | - ns |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>      |   |  | =    | 28    | 42    |      |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>           |   |  | =    | 13    | 20    |      |
| Source-Drain Diode Ratings and Chara          | acteristics <sup>b</sup> |   |  |      | _     |       |      |
| Pulsed Current <sup>a</sup>                   | I <sub>SM</sub>          |   |  | -    | -     | - 20  | Α    |
| Forward Voltage                               | $V_{SD}$                 | I <sub>F</sub> = - 2 A, V <sub>GS</sub> = 0 V   |  | -    | - 0.8 | - 1.2 | V    |

#### Notes

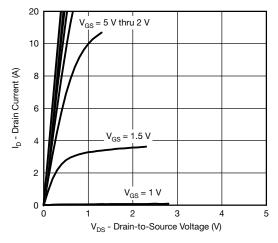
- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

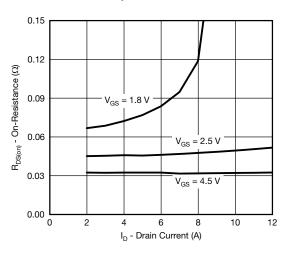
2



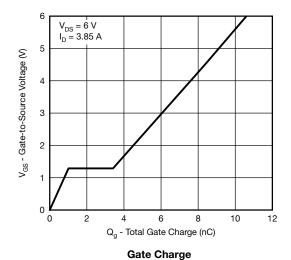
## **TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}\text{C}$ , unless otherwise noted)

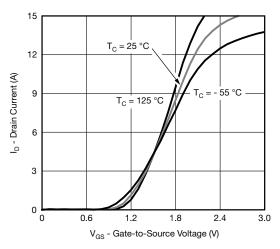


#### **Output Characteristics**

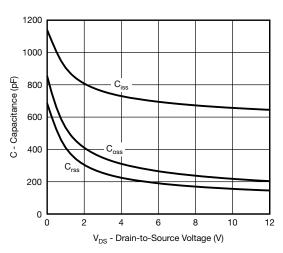


**On-Resistance vs. Drain Current** 

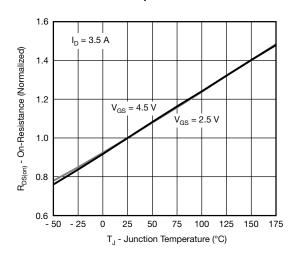




**Transfer Characteristics** 



Capacitance

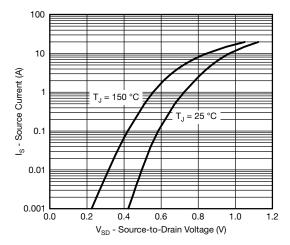


On-Resistance vs. Junction Temperature

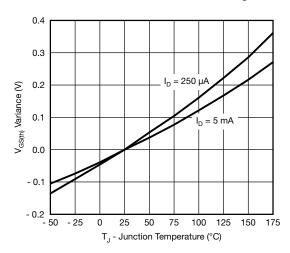
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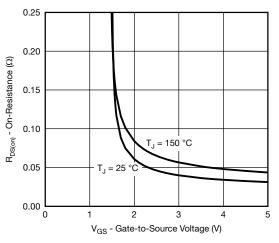
### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \, ^{\circ}C$ , unless otherwise noted)



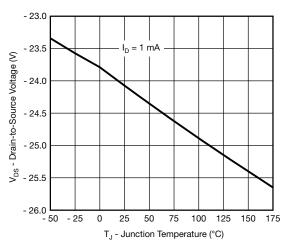
#### Source-Drain Diode Forward Voltage



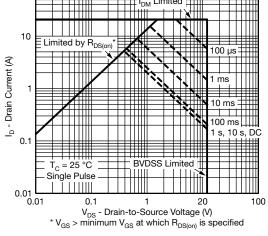
**Threshold Voltage** 



On-Resistance vs. Gate-to-Source Voltage



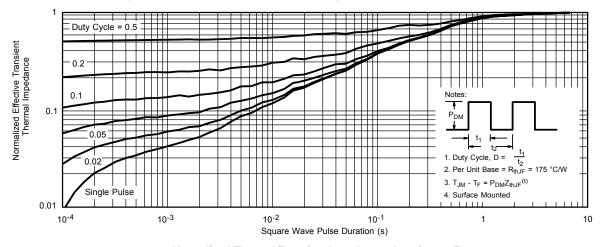
**Drain Source Breakdown vs. Junction Temperature** 



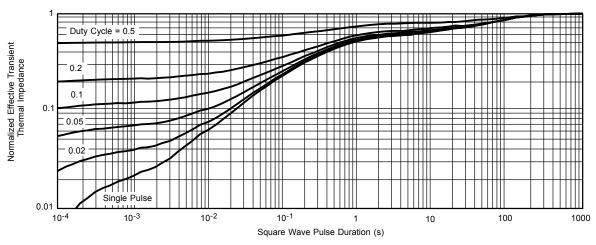
Safe Operating Area



#### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Foot



Normalized Thermal Transient Impedance, Junction-to-Ambient

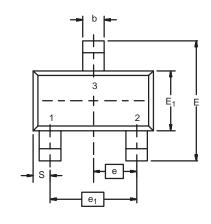
#### Note

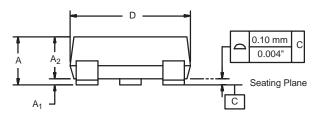
- · The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



## SOT-23 (TO-236): 3-LEAD





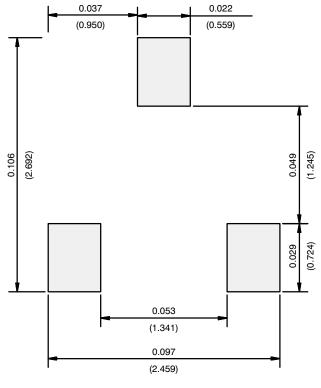


| Dim -                    | MILLIM   | IETERS | INCHES             |       |  |
|--------------------------|----------|--------|--------------------|-------|--|
|                          | Min      | Max    | Min                | Max   |  |
| Α                        | 0.89     | 1.12   | 0.035              | 0.044 |  |
| A <sub>1</sub>           | 0.01     | 0.10   | 0.0004             | 0.004 |  |
| A <sub>2</sub>           | 0.88     | 1.02   | 0.0346             | 0.040 |  |
| b                        | 0.35     | 0.50   | 0.014              | 0.020 |  |
| С                        | 0.085    | 0.18   | 0.003              | 0.007 |  |
| D                        | 2.80     | 3.04   | 0.110              | 0.120 |  |
| E                        | 2.10     | 2.64   | 0.083              | 0.104 |  |
| E <sub>1</sub>           | 1.20     | 1.40   | 0.047              | 0.055 |  |
| е                        | 0.95 BSC |        | 0.0374 Ref         |       |  |
| e <sub>1</sub>           | 1.90 BSC |        | 0.0748 Ref         |       |  |
| L                        | 0.40     | 0.60   | 0.016              | 0.024 |  |
| L <sub>1</sub>           | 0.64 Ref |        | 0.025              | S Ref |  |
| S                        | 0.50 Ref |        | 0.50 Ref 0.020 Ref |       |  |
| q                        | 3°       | 8°     | 3°                 | 8°    |  |
| ECN: S-03946-Rev. K. 09- | Jul-01   |        |                    |       |  |

DWG: 5479



### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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